

ULTRAFAST SOFT RECOVERY RECTIFIER DIODE

PRODUCT APPLICATIONS

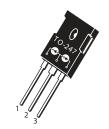
- Anti-Parallel Diode -Switchmode Power Supply
 - -Inverters
- Free Wheeling Diode
 - -Motor Controllers
 - -Converters
 - -Inverters
- · Snubber Diode
- PFC
- RoHS Compliant

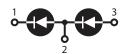
PRODUCT FEATURES

- Ultrafast Recovery Time
- Soft Recovery Characteristics
- · Popular TO-247 Package
- · Low Forward Voltage
- · Low Leakage Current
- Avalanche Energy Rated

PRODUCT BENEFITS

- Low Losses
- · Low Noise Switching
- Cooler Operation
- · Higher Reliability Systems
- Increased System Power Density





- 1 Cathode 1 Anode 1
- Cathode 2
- 3 Anode 2

MAXIMUM RATINGS

All Ratings per diode: $T_C = 25^{\circ}C$ unless otherwise specified.

Symbol	Parameter	Ratings	Unit
V_R	Maximum D.C. Reverse Voltage		
V _{RRM}	Maximum Peak Repetitive Reverse Voltage	1200	V
V_{RWM}	Maximum Working Peak Reverse Voltage		
I _{F(AV)}	Maximum Average Forward Current (T _c = 74°C, Duty Cycle = 0.5)	15	
I _{F(RMS)}	RMS Forward Current (Square wave, 50% duty)	17	Α
I _{FSM}	Non-Repetitive Forward Surge Current (T _J = 45°C, 8.3ms)	110	
E _{AVL}	Avalanche Energy (1A, 40mH)	20	mJ
T_{J},T_{STG}	Operating and StorageTemperature Range	-55 to 175	°C
T _L	Lead Temperature for 10 Sec.	300	

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Parameter		MIN	TYP	MAX	Unit
V _F	Forward Voltage	I _F = 15A		3.0	3.5	V
		I _F = 30A		3.7		
		I _F = 15A, T _J = 125°C		2.2		
I _{RM}	Maximum Reverse Leakage Current	V _R = 1200V			100	μA
		V _R = 1200V, T _J = 125°C			500	
C _T	Junction Capacitance, V _R = 200V	V _R = 200V		17		

CAUTION: These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

DYNAMIC CHARACTERISTICS

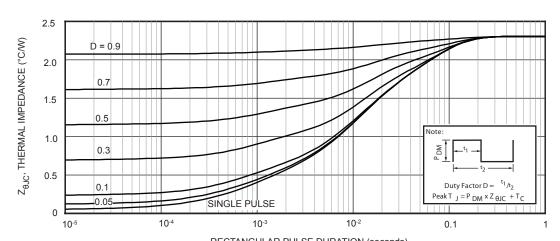
APT15DQ120BHB(G)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
t _{rr}	Reverse Recovery Time	$I_F = 1A$, $di_F/dt = -100A/\mu s$ $V_R = 30V$, $T_J = 25^{\circ}C$		21		ns
t _{rr}	Reverse Recovery Time	I _F = 15A, di _F /dt = -200A/µs V _R = 800V, T _C = 25°C		240		
Q_{rr}	Reverse Recovery Charge			260		nC
I _{RRM}	Reverse Recovery Current			3		Amps
t _{rr}	Reverse Recovery Time	$I_F = 15A, di_F/dt = -200A/\mu s$ $V_R = 800V, T_C = 125^{\circ}C$		290		ns
Q_{rr}	Reverse Recovery Charge			960		nC
I _{RRM}	Reverse Recovery Current			6		Amps
t _{rr}	Reverse Recovery Time	$I_F = 15A, di_F/dt = -1000A/\mu s$ $V_R = 800V, T_C = 125^{\circ}C$		130		ns
Q _{rr}	Reverse Recovery Charge			1340		nC
I _{RRM}	Maximum Reverse Recovery Current			19		Amps

THERMAL AND MECHANICAL CHARACTERISTICS

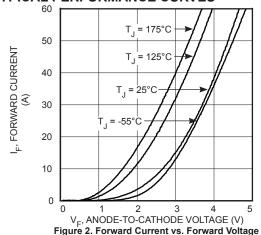
Symbol	Parameter	Min	Тур	Max	Unit
R _{eJC}	Reverse Recovery Time			2.3	°C/W
W _T	Package Weight		0.22		oz
			5.9		g
Torque	Maximum Mounting Torque			10	lb•in
				1.1	N•m

Microsemi reserves the right to change, without notice, the specifications and information contained herein.



RECTANGULAR PULSE DURATION (seconds)
FIGURE 1. MAXIMUM EFFECTIVE TRANSIENT THERMAL IMPEDANCE, JUNCTION-TO-CASE vs. PULSE DURATION

TYPICAL PERFORMANCE CURVES



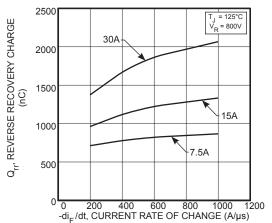


Figure 4. Reverse Recovery Charge vs. Current Rate of Change

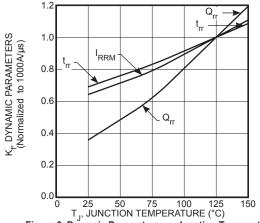


Figure 6. Dynamic Parameters vs. Junction Temperature

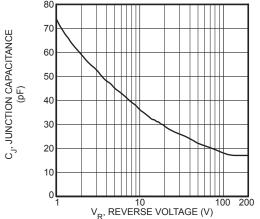


Figure 8. Junction Capacitance vs. Reverse Voltage

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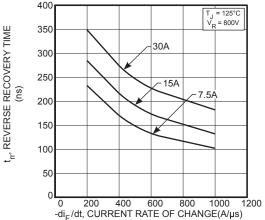


Figure 3. Reverse Recovery Time vs. Current Rate of Change

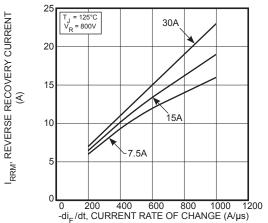


Figure 5. Reverse Recovery Current vs. Current Rate of Change

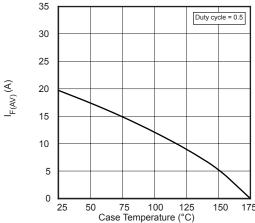


Figure 7. Maximum Average Forward Current vs. CaseTemperature

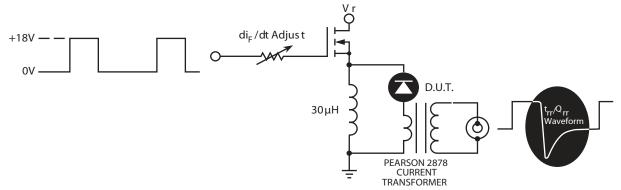


Figure 9. Diode Test Circuit

- 1 I_F Forward Conduction Current
- 2 di_c/dt Rate of Diode Current Change Through Zero Crossing.
- 3 I_{RRM} Maximum Reverse Recovery Current
- 4 t_{rr} Reverse Recovery Time measured from zero crossing where diode current goes from positive to negative, to the point at which the straight line through I_{RRM} and 0.25, I_{RRM} passes through zero.
- $\mathbf{5}$ \mathbf{Q}_{rr} Area Under the Curve Defined by $\mathbf{I}_{\mathrm{RRM}}$ and \mathbf{t}_{RR}

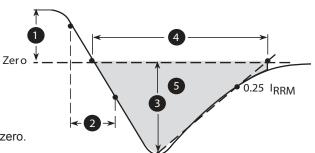
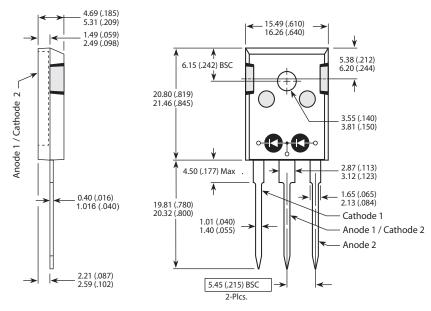


Figure 10. Diode Reverse Recovery Waveform Definition

TO-247 Package Outline

@1 SAC: Tin, Silver, Copper



Dimensions in Millimeters and (Inches)

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